

A Global Leader of Green Environment & Energy

PLASMATECH









Large-sized WET-EP System

- Equipment that treats fine dust and harmful white smoke using wet electric precipitation using corona discharge
- · Secondary pollutant removal and prevention of civil complaints
- · Eco-friendly technology business
- Business expansion in related application areas
- · Removal efficiency verification completed
- · Secured power supply design technology
- · Secured fine spray technology

Small and Medium-sized WET-EP System

- Load problems in old buildings arose as existing white smoke removal systems were installed on the roof with a large capacity (300 to 1,200CMM)
- Designed as a small white smoke removal system to be installed inside (FAB), not on the roof of the buildings



Plasma Scrubber

- \cdot Equipment that processes toxic gas generated in the semiconductor production process inside the FAB (primary scrubber or P.O.U. (Point of Unit))
- · Secured Own technological capabilities using plasma
- · Easy installation and system implementation through miniaturization and standardization

Nano Powder Manufacturing System

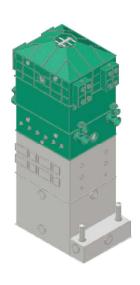
- Equipment that produces metal (nickel) nano powder using high-temperature plasma
- · Used as a powder for MLCC electrodes
- Nickel powder production
 Equipment used in the MLCC
 (Multi-Layer Ceramic Capacitor) process
- System verification completed through the development of proprietary plasma technology



Large-sized WET-EP (Electric Precipitation) System

Usage

Fine particles and harmful white smoke removal device with harmful gas removal performance results that are greater than 3 times better than conventional scrubbers by aggregating fine particles that are difficult to collect with water droplets of strong dielectric properties, using the electrostatic dielectric method on harmful exhaust gas emitted after manufacturing semiconductors in general industrial facilities





Core Technology

- · Harmful white smoke removal efficiency
- · Secured power supply design technology
- · Secured fine spray technology
- · Secondary pollutant removal and prevention of civil complaints
- · Eco-friendly technology company image enhancing

Features

- · Efficiency verified for dust and harmful white smoke through 15 years of product delivery electrically stable design and perfect high voltage control
- · Easy maintenance and repair · Self-cleaning system applied
- · Customized design and manufacture according to the on-site situation



Before Operation







Approximately 96% or Higher





Small and Medium-sized WET-EP (Electric Precipitation) System

Outline

Features

Applied Areas Unlike the large-sized WET-EP installed on the roof, this equipment is installed inside the FAB and can be swapped out without affecting the main process through the installation of the back-up line during P.M. and maintenance, improving production and preventing air pollution.

- \cdot Designed to be installed inside semiconductor factories as a small WET-EP system of 5 to 300CMM
- Problems of installing the existing, large-sized ones on the roofs of semiconductor factories (lack of space, installation difficulty due to equipment load, and pipe clogging inside the FAB) are solved by installation inside (FAB)
- · Minimized size (2M*2M*2M) implemented (5CMM based)
- · Able to be installed in domestic and overseas semiconductor and LCD buildings (FAB)
- · DEMO facilities planned for an Austrian semiconductor company.

Processing Capacity	500CMM *Available by specification (300 to 15,00CMM
Equipment Size	2,000 × 2,000 × 2,000 (H)mm
Power Consumption	15 kW.hr
Superficial Velocity (Design Velocity)	1.0m/s
Pressure Loss	30mmAq or less
Discharge Method	Corona discharge (Pin discharge)
Heater	Cartridge Type(3kw/4ea)
Purge blower	30 CMM×170 mmAq, 2.2kW
Precipitation Transformer Rectifier	40KV/100mA
TR Control panel	Built-in
PLC Control panel	Built-in
MCC Panel	Built-in
Precipitation Unit Weight	2t





Plasma Scrubber (Semiconductor Waste Gas Treatment Technology)

The equipment that processes harmful gas generated through the semiconductor production process inside the FAB before being discharged as exhaust (for explosive, toxic, and corrosive gas treatment purpose).



Cleaning gas



























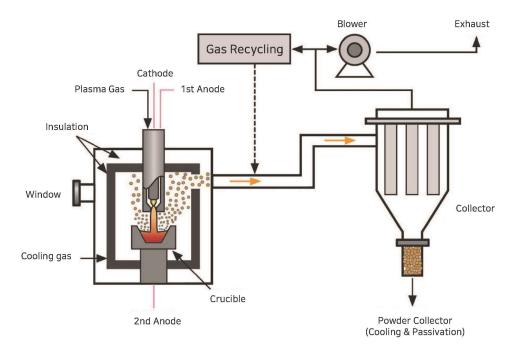


CF4, CH₃F





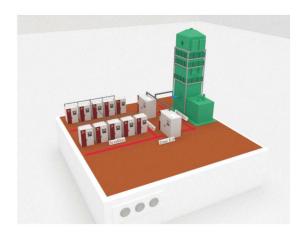
Nano Powder Manufacturing Process



Primary Scrubber

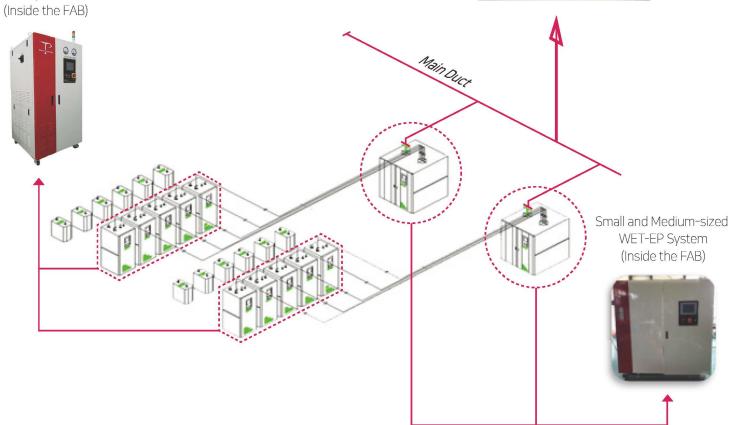
WET-EP Semiconductor FAB Configuration Diagram

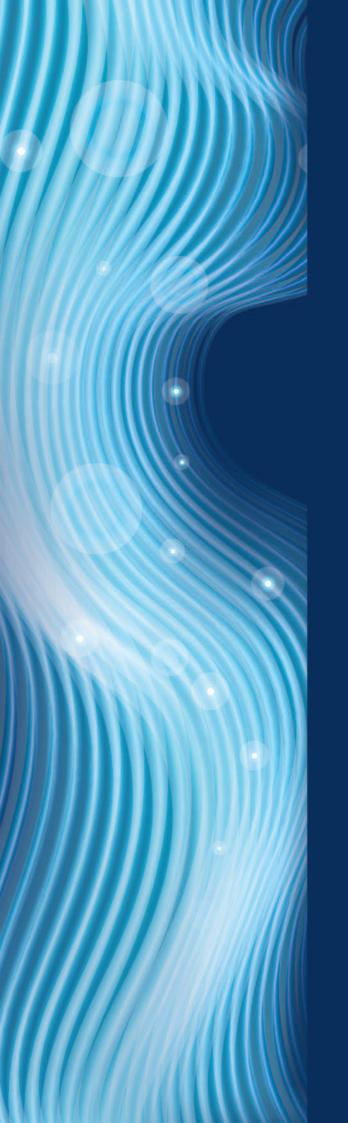
- Large quantity of fine particles are generated through the process of decomposing and treating gas generated in the semiconductor FAB process in the primary scrubber and treated in the small and medium-sized WET-EP system
- Equipment capacity is designed for 5 to 300CMM according to the number of primary scrubbers



Large-sized WET-EP System (Roof Outside the FAB)







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